

C1206C223KATACTU

Aliases (C1206C223KATAC7800)

SMD Comm X8G HT150C, Ceramic, 0.022 uF, 10%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	36 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	1206	
L	3.2mm +/-0.2mm	
W	1.6mm +/-0.2mm	
Т	1.6mm +/-0.20mm	
S	1.5mm MIN	
В	0.5mm +/-0.25mm	

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Т	1.6mm +/-0.20mm
S	1.5mm MIN
В	0.5mm +/-0.25mm
Packaging Specifications	

2000

Packaging

Packaging Quantity

Specifications		
Capacitance	0.022 uF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	10%	
Voltage DC	250 VDC	
Dielectric Withstanding Voltage	625 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	45.4545 GOhms	

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Insulation Resistance	45.4545 GOhm

T&R, 180mm, Plastic Tape

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